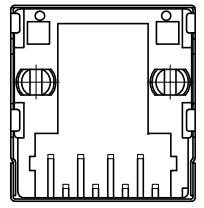


PC Board Layout
Component Side Shown



NOTES:

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.30mm.
3. PLATING :SELECTING GOLD PLATING 3u"~50u" OVER NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER AREA
4. SHIELD: :0.20mm THICKNESS COPPER ALLY WITH NICKEL PLATED

ELECTRICAL:

1. VOLTAGE RATING :125 VAC RMS.
2. CURRENT RATING :1.5 AMP.
3. CONTACT RESISTANCE :30 MILLIOHMS MAX.
4. INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

1. DURRABILITY: :750 CYCLES MIN.
2. PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40° C TO 85° C.
2. OPERATION : 0° C TO 70° C.

REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD

DETACHED LISTS	MM (INCH)		DFTO: SHB	DATE: 2007.05.05	Coorle Technology
	TOLERANCES EXCEPT AS NOTED		CHKD: LANBD	DATE: 2007.05.05	
			MFO:	DATE:	
			APPVL:	DATE:	
MM		MATERIAL :		TITLE Modular Jack 5224 8P8CS	
.0 ± 0.15 ±				FOOT BACK 3.05	
.00 ± 0.075 ±		QT'Y :		DRAWING NO.	
.000 ± 0.05 ±		FINISH :		/PART NO.	
ANGLES ± 0.5		SCALE :		DO NOT SCALE DRAWING	
THIRD ANGLE PROJECTION				SHEET OF	